



Foresite Umpire Board Test Designations

All of the test patterns on the Umpire board have a designation. The following table shows what those patterns are and their intended usage.

Test Pattern Designation	Description	Used For:
PGA1	PGA Pattern _ Alternating rows of PTHs	Testing for flux entrapment under large sockets.
QFP1	0.5 mm pitch QFP – pad to pad	Tests for the effects of solder paste residues on fine pitch parts.
QFP2	0.5mm pitch QFP – comb pattern	Tests for residues under fine pitch parts.
LCC1	681/OLCC – pad to pad	Tests for the effects of residues between leads of low standoff devices (could also be a PLCC if desired).
LCC2	Comb pattern under 681/OLCC	Tests for residues under low stand off devices.
BGA1	Alternating rows of pads on a 272 bump BGA	Tests for residues under a BGA.
DIP1	14 pin DIP – hole to hole	Tests for effects of residues between leads of CERDIPs.
DIP2	14 pin DIP – Y pattern under DIP	Tests for effects of residues under DIPs.
HEAD1	Header pattern – top side	Tests for the effects of paste residues.
HEAD2	Second header pattern – top side	Tests for paste residue and cored wire flux residues, possibly latex mask.
HEAD3	Header pattern – bottom side	Tests for past/flux interactions on wave side, possibly latex mask on bottom side.
B24-1	Half of an IPC-B-24 comb – no mask	Tests for interactions between laminate, metal and flux.
B24-2	Half of an IPC-B-24 comb – fully masked	Tests for interactions between flux and solder mask.
B24-3	Half of an IPC-B-24 comb – cross hatched mask	Tests for entrapment effects of mask on flux.
0805	Row of 0805 pads/chips	Tests for the effects of paste, flux and adhesive on small parts.
1206	Row of 1206 pds/chips	Tests for the effects of paste, flux and adhesive on small parts.